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## INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Not for submission under 37 CFR 1.99) Application Number Filing Date First Named Inventor Hiroki WAKAMATSU Art Unit Examiner Name Attorney Docket Number 36856.1438

				U.S	.PATENTS			
Examiner Initial*	Cite No	Patent Number	Kind Code <sup>1</sup>	Issue Date	Name of Patentee or Applicant of cited Document	Pages,Columns,Lines where Relevant Passages or Relevant Figures Appear		
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Kida et al.

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Receipt date: 05/05/2006	Application Number	10595698 - GAU: 2833		
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INFORMATION DISCLOSURE	First Named Inventor	Hiroki	WAKAMATSU	
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